

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.43261	100.0	1
Subtotal				0.43261	100	1
Post-plating	Tin solder	Bismuth (Bi)	7440-69-9	0	0.0	0
	Tin solder	Tin (Sn)	7440-31-5	1.59183	99.99	3.67963
	Tin solder	Copper (Cu)	7440-50-8	0	0.0	0
	Tin solder	Lead (Pb)	7439-92-1	0.00016	0.01	0.00037
	Tin solder	Antimony (Sb)	7440-36-0	0	0.0	0
	Subtotal				1.59199	100
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.01199	0.03	0.02772
	Copper alloy	Iron (Fe)	7439-89-6	0.03997	0.1	0.09239
	Copper alloy	Copper (Cu)	7440-50-8	39.80856	99.6	92.02044
	Pure metal layer	Silver (Ag)	7440-22-4	0.10791	0.27	0.24945
	Subtotal				39.96843	100
Adhesive	Polymer	Paraffin wax	8002-74-2	0.18516	20.0	0.428
	Polymer	Epoxy resin system		0.07406	8.0	0.1712
	Filler	Silver (Ag)	7440-22-4	0.66656	72.0	1.5408
	Subtotal				0.92578	100
Mould Compound	Polymer	Tetrabromobisphenol A/Epichlorohydrin polymer	40039-93-8	1.42457	2.5	3.293
	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	4.27371	7.5	9.879
	Filler	Silica -amorphous-	7631-86-9	21.08364	37.0	48.7364
	Pigment	Carbon black	1333-86-4	0.28491	0.5	0.6586
	Polymer	Epoxy resin system		8.54742	15.0	19.758
	Filler	Silicon Dioxide (SiO2)	14808-60-7	21.08364	37.0	48.7364
	Flame retardant	Antimony Trioxide (Sb2O3) - cas no. 1309-64-4	1309-64-4	0.28491	0.5	0.6586
	Subtotal				56.9828	100
Wire	Pure metal	Gold (Au)	7440-57-5	0.09837	100.0	0.2274
	Subtotal				0.09837	100
Total				99.99998	100	231.1574

Disclaimer

All information in this document is furnished for exploratory or indicative purposes only. All information in this document is believed to be accurate and reliable. However, WeEn Semiconductors does not give any representations or warranties as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. WeEn Semiconductors may make changes to information published in this document at any time and without notice. Minor deviations may occur in the products from different manufacturing location. This document supersedes and replaces all information supplied prior to the publication hereof. Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.